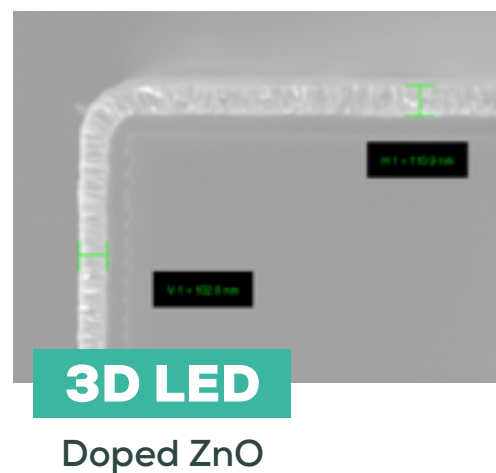
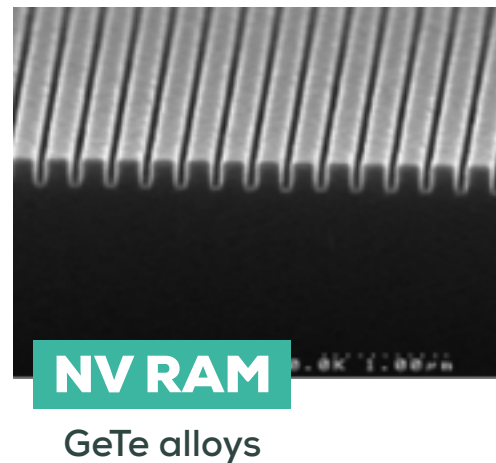
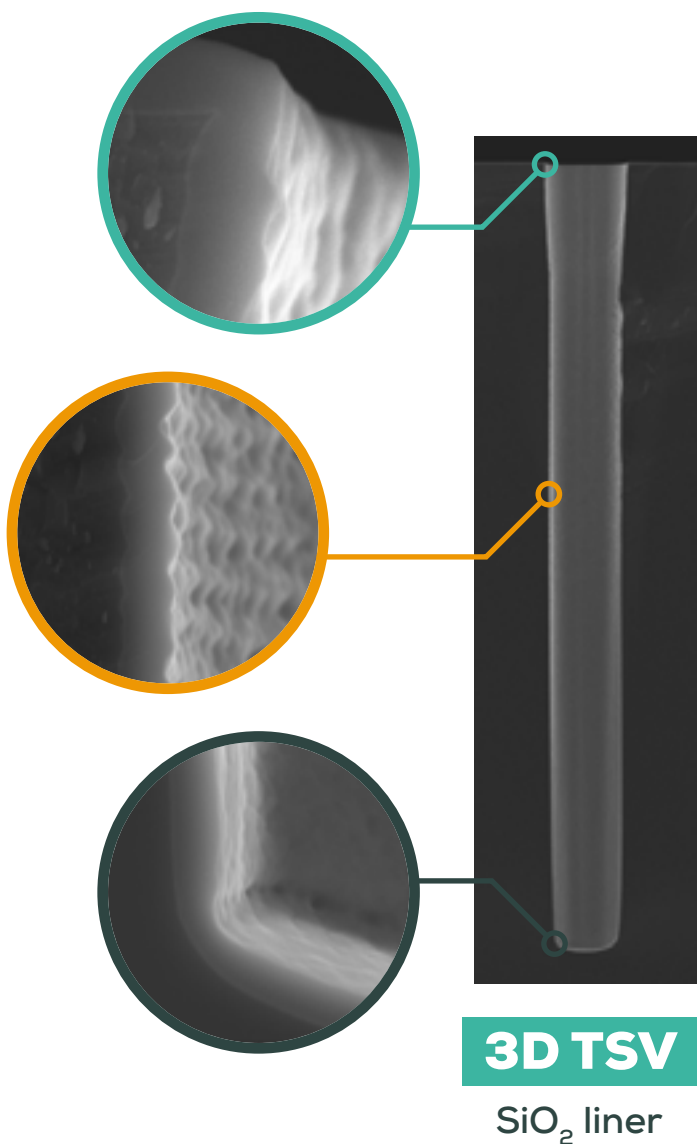


- At the crossroads of CVD and ALD deposition techniques
- ALD film performances at CVD speed
- Unique film properties
- Best in class solution for Thick and Conformal layers



When Thick & Conformal matters

Unique process control

- Temporal control
→ Better film properties
- Separate species inlets
→ No parasitic reactions
- High reaction rate
→ Lower precursor consumption & Higher deposition rate
- Precise Volume introduction
→ Repeatability

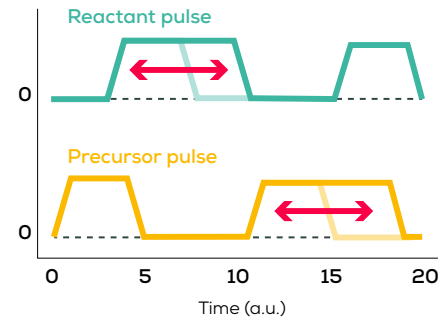
Features

- Plasma enhanced deposition
- Unique in-situ cleaning capability
- Single wafer process module
- Low cost of ownership

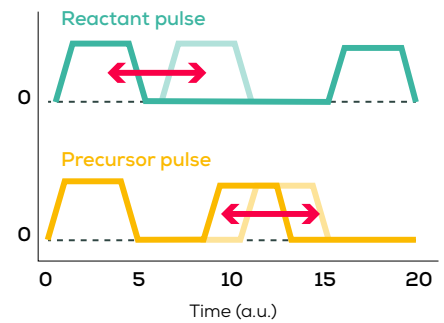


Extended Process Window

PRECURSOR AND REACTANT
PULSES DURATION CUSTOMIZATION



PRECURSOR AND REACTANT
PULSES POSITION CUSTOMIZATION



FAST

ALD

PECVD

Deposition rate
Process window
Conformality
Film quality
In-situ cleaning

